



## 32K × 8 CMOS STATIC RAM

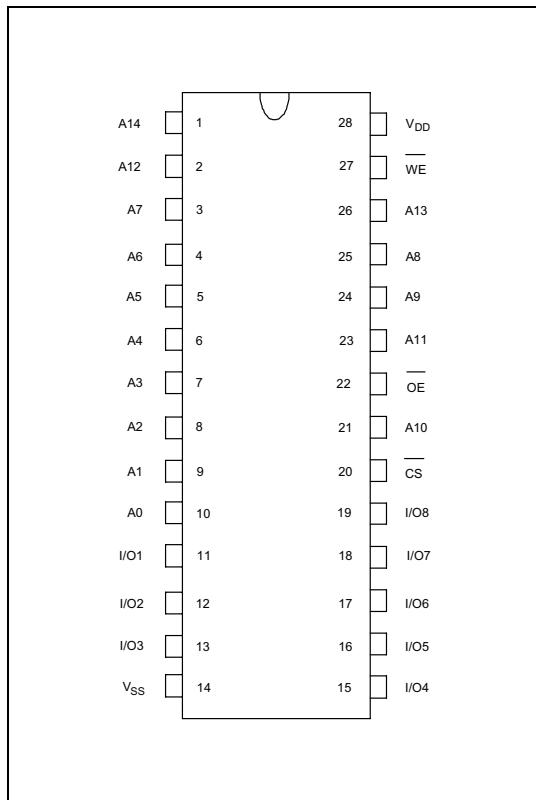
### GENERAL DESCRIPTION

The W24257 is a slow speed, low power CMOS static RAM organized as 32768 × 8 bits that operates on a single 5-volt power supply. This device is manufactured using Winbond's high performance CMOS technology.

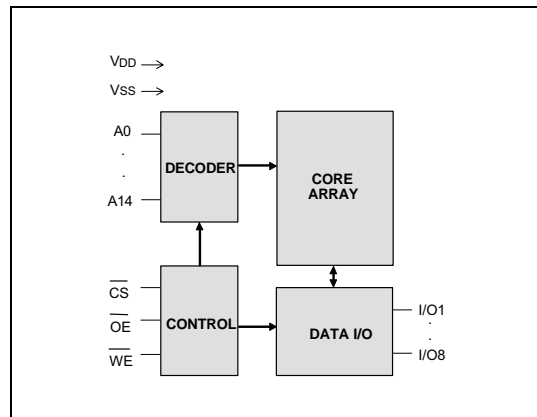
### FEATURES

- Low power consumption:
  - Active: 325 mW (max.)
  - Standby: 75 μW (max.) (LL-version)  
150 μW (max.) (L-version)
- Access time: 70 nS (max.)
- Single +5V power supply
- Fully static operation
- All inputs and outputs directly TTL compatible
- Three-state outputs
- Battery back-up operation capability
- Data retention voltage: 2V (min.)
- Packaged in 28-pin 330 mil SOP, standard type one TSOP (8 mm x 13.4 mm )

### PIN CONFIGURATION



### BLOCK DIAGRAM



### PIN DESCRIPTION

SYMBOL	DESCRIPTION
A0–A14	Address Inputs
I/O1–I/O8	Data Inputs/Outputs
CS	Chip Select Input
WE	Write Enable Input
OE	Output Enable Input
VDD	Power Supply
VSS	Ground



## TRUTH TABLE

$\overline{CS}$	$\overline{OE}$	$\overline{WE}$	MODE	I/O1–I/O8	V <sub>DD</sub> CURRENT
H	X	X	Not Selected	High Z	ISB, ISB1
L	H	H	Output Disable	High Z	I <sub>DD</sub>
L	L	H	Read	Data Out	I <sub>DD</sub>
L	X	L	Write	Data In	I <sub>DD</sub>

## DC CHARACTERISTICS

### Absolute Maximum Ratings

PARAMETER	RATING	UNIT
Supply Voltage to V <sub>SS</sub> Potential	-0.5 to +7.0	V
Input/Output to V <sub>SS</sub> Potential	-0.5 to V <sub>DD</sub> +0.5	V
Allowable Power Dissipation	1.0	W
Storage Temperature	-65 to +150	°C
Operating Temperature	0 to +70	°C

Note: Exposure to conditions beyond those listed under Absolute Maximum Ratings may adversely affect the life and reliability of the device.

### Operating Characteristics

(V<sub>DD</sub> = 5V ±10%, V<sub>SS</sub> = 0V, T<sub>A</sub> = 0 to 70° C)

PARAMETER	SYM.	TEST CONDITIONS	MIN.	TYP.	MAX.	UNIT
Input Low Voltage	V <sub>IL</sub>	-	-0.5	-	+0.8	V
Input High Voltage	V <sub>IH</sub>	-	+2.2	-	V <sub>DD</sub> +0.5	V
Input Leakage Current	I <sub>LI</sub>	V <sub>IN</sub> = V <sub>SS</sub> to V <sub>DD</sub>	-2	-	+2	μA
Output Leakage Current	I <sub>LO</sub>	V <sub>I/O</sub> = V <sub>SS</sub> to V <sub>DD</sub> , $\overline{CS}$ = V <sub>IH</sub> (min.) or $\overline{OE}$ = V <sub>IH</sub> (min.) or $\overline{WE}$ = V <sub>IL</sub> (max.)	-2	-	+2	μA
Output Low Voltage	V <sub>OL</sub>	I <sub>OL</sub> = +4.0 mA	-	-	0.4	V
Output High Voltage	V <sub>OH</sub>	I <sub>OH</sub> = -1.0 mA	2.4	-	-	V
Operating Power Supply Current	I <sub>DD</sub>	$\overline{CS}$ = V <sub>IL</sub> (min.), I/O = 0 mA Cycle = min., Duty = 100%	-	-	65	mA
Standby Power Supply Current	ISB	$\overline{CS}$ = V <sub>IH</sub> (min.) Cycle = min., Duty = 100%	-	-	3	mA
	ISB1	$\overline{CS} \geq V_{DD} - 0.2V$	LL	-	15	μA
			L	-	30	μA

Note: Typical characteristics are at V<sub>DD</sub> = 5V, T<sub>A</sub> = 25° C.



## CAPACITANCE

(V<sub>DD</sub> = 5V, T<sub>A</sub> = 25° C, f = 1 MHz)

PARAMETER	SYM.	CONDITIONS	MAX.	UNIT
Input Capacitance	C <sub>IN</sub>	V <sub>IN</sub> = 0V	6	pF
Input/Output Capacitance	C <sub>I/O</sub>	V <sub>OUT</sub> = 0V	8	pF

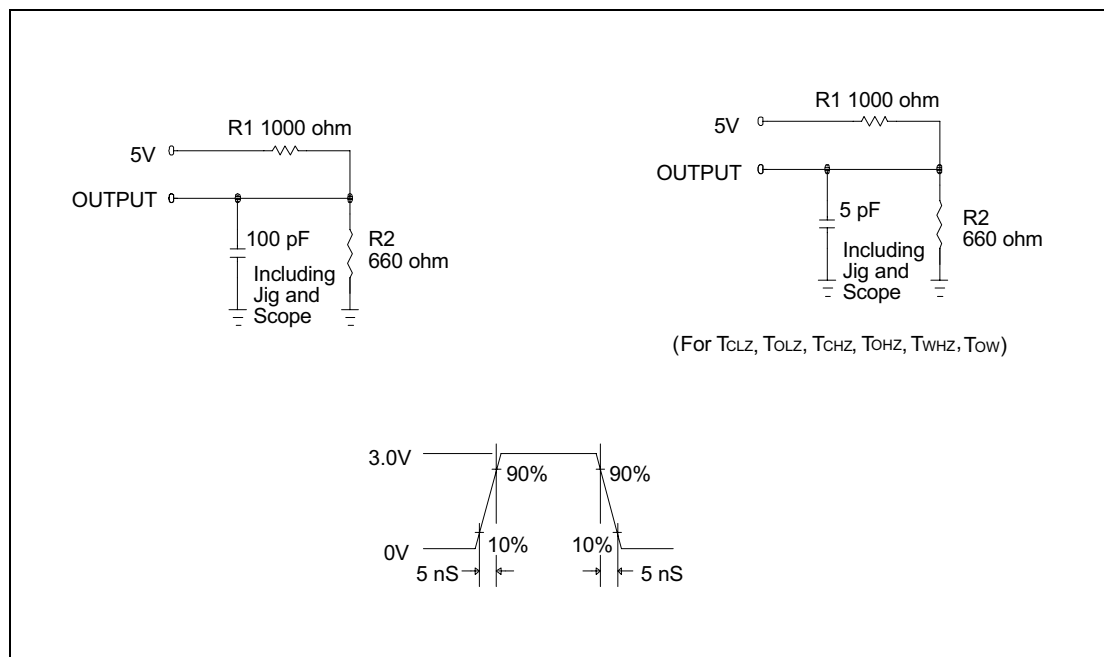
Note: These parameters are sampled but not 100% tested.

## AC CHARACTERISTICS

### AC Test Conditions

PARAMETER	CONDITIONS
Input Pulse Levels	0.6V to 2.4V
Input Rise and Fall Times	5 nS
Input and Output Timing Reference Level	1.5V
Output Load	CL = 100 pF, I <sub>OH</sub> /I <sub>OL</sub> = -1 mA/4 mA

### AC Test Loads and Waveform





AC Characteristics, continued

(V<sub>DD</sub> = 5V ±10%, V<sub>SS</sub> = 0V, T<sub>A</sub> = 0 to 70° C)**Read Cycle**

PARAMETER	SYMBOL	W24257-70		UNIT
		MIN.	MAX.	
Read Cycle Time	TRC	70	-	nS
Address Access Time	TAA	-	70	nS
Chip Select Access Time	TACS	-	70	nS
Output Enable to Output Valid	TAOE	-	35	nS
Chip Selection to Output in Low Z	TCLZ*	10	-	nS
Output Enable to Output in Low Z	TOLZ*	5	-	nS
Chip Deselection to Output in High Z	TCHZ*	-	30	nS
Output Disable to Output in High Z	TOHZ*	-	30	nS
Output Hold from Address Change	TOH	10	-	nS

\* These parameters are sampled but not 100% tested

**Write Cycle**

PARAMETER		SYMBOL	W24257-70		UNIT
			MIN.	MAX.	
Write Cycle Time		TWC	70	-	nS
Chip Selection to End of Write		TCW	60	-	nS
Address Valid to End of Write		TAW	60	-	nS
Address Setup Time		TAS	0	-	nS
Write Pulse Width		TWP	45	-	nS
Write Recovery Time	$\overline{CS}, \overline{WE}$	TWR	0	-	nS
Data Valid to End of Write		TDW	30	-	nS
Data Hold from End of Write		TDH	0	-	nS
Write to Output in High Z		TWHZ*	-	30	nS
Output Disable to Output in High Z		TOHZ*	-	30	nS
Output Active from End of Write		TOW	0	-	nS

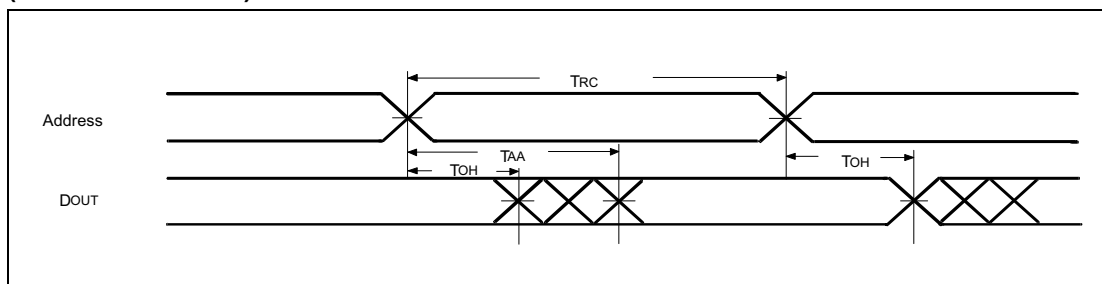
\* These parameters are sampled but not 100% tested



## TIMING WAVEFORMS

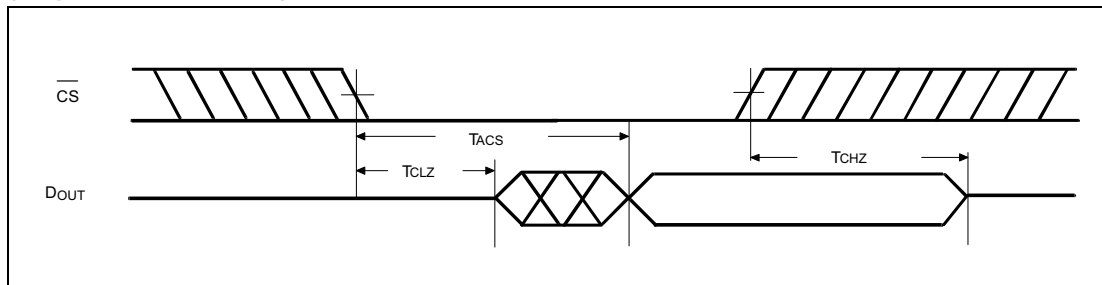
### Read Cycle 1

(Address Controlled)



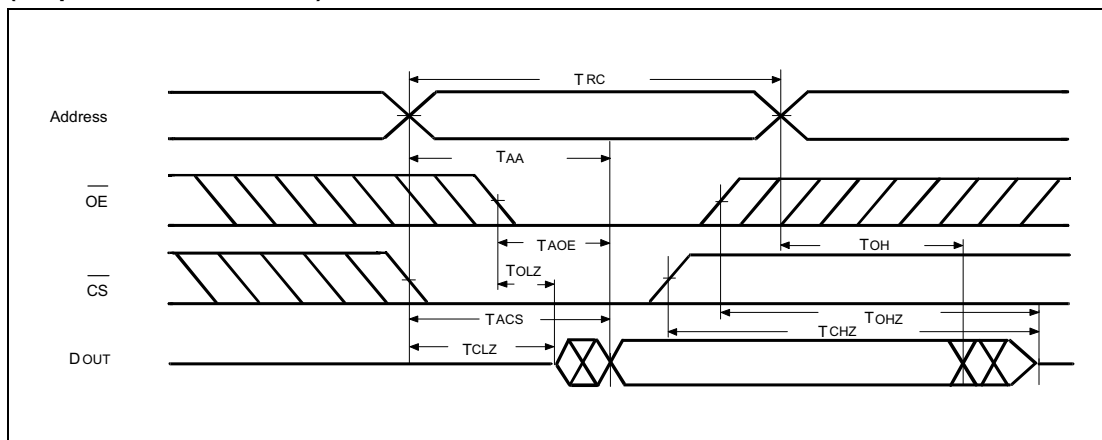
### Read Cycle 2

(Chip Select Controlled)



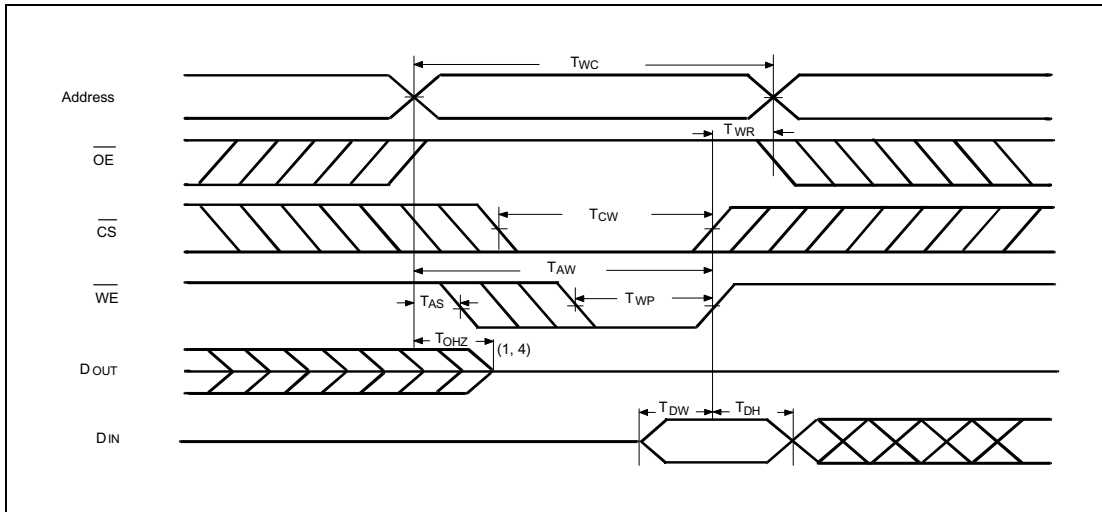
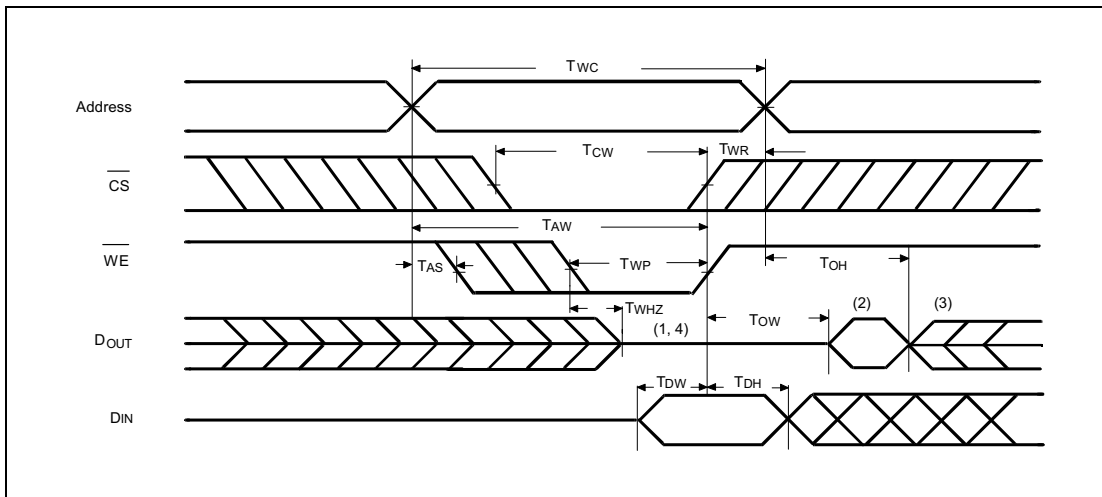
### Read Cycle 3

(Output Enable Controlled)





Timing Waveforms, continued

**Write Cycle 1****Write Cycle 2****( $\overline{OE} = V_{IL}$  Fixed)**

Notes:

1. During this period, I/O pins are in the output state, so input signals of opposite phase to the outputs should not be applied.
2. The data output from DOUT are the same as the data written to DIN during the write cycle.
3. DOUT provides the read data for the next address.
4. Transition is measured  $\pm 500$  mV from steady state with  $C_L = 5$  pF. This parameter is guaranteed but not 100% tested.



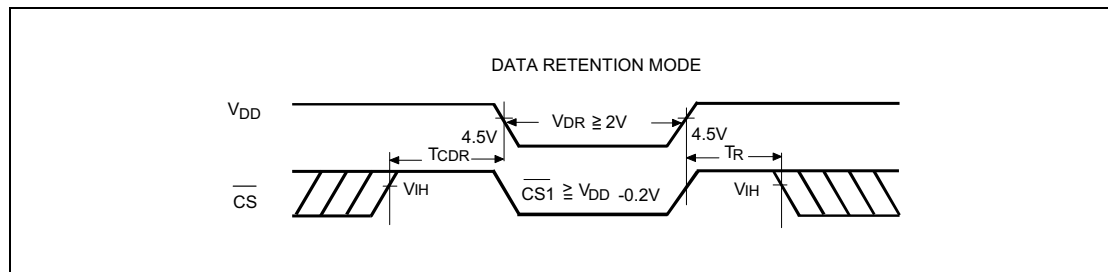
## DATA RETENTION CHARACTERISTICS

(TA = 0 to 70° C)

PARAMETER	SYM.	TEST CONDITIONS	MIN.	TYP.	MAX.	UNIT
VDD for Data Retention	VDR	$\overline{CS} \geq V_{DD} - 0.2V$	2.0	-	-	V
Data Retention Current	IDDDR	$\overline{CS} \geq V_{DD} - 0.2V$	LL	-	-	15 $\mu A$
		$V_{DD} = 3V$	L	-	-	30 $\mu A$
Chip Deselect to Data Retention Time	TCDR	See data retention	0	-	-	nS
Operation Recovery Time	TR	waveform	TRC*	-	-	nS

TRC\* = Read Cycle Time

## DATA RETENTION WAVEFORM



## ORDERING INFORMATION

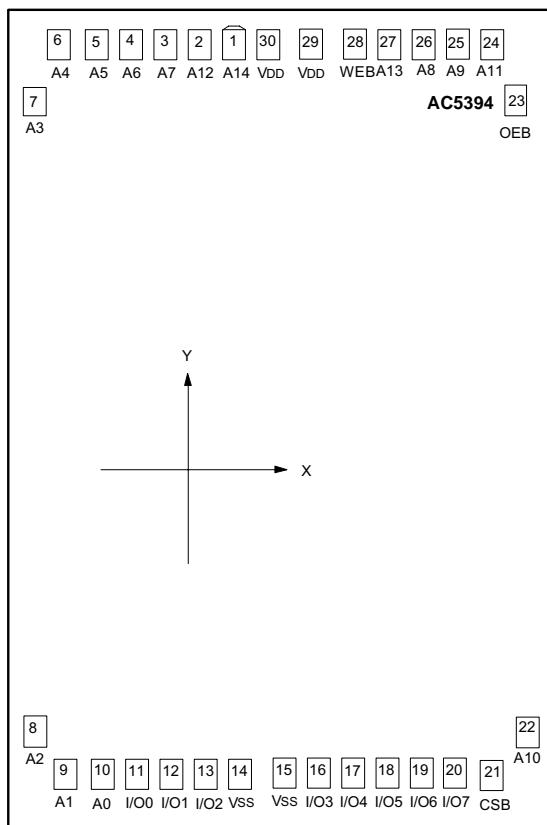
PART NO.	ACCESS TIME (nS)	OPERATING CURRENT MAX. (mA)	STANDBY CURRENT MAX. ( $\mu A$ )	PACKAGE
W24257S-70LL	70	65	15	330 mil SOP
W24257S-70L	70	65	30	330 mil SOP
W24257Q-70LL	70	65	15	Standard type one TSOP
W24257Q-70L	70	65	30	Standard type one TSOP

Notes:

- Winbond reserves the right to make changes to its products without prior notice.
- Purchasers are responsible for performing appropriate quality assurance testing on products intended for use in applications where personal injury might occur as a consequence of product failure.



## BONDING PAD DIAGRAM



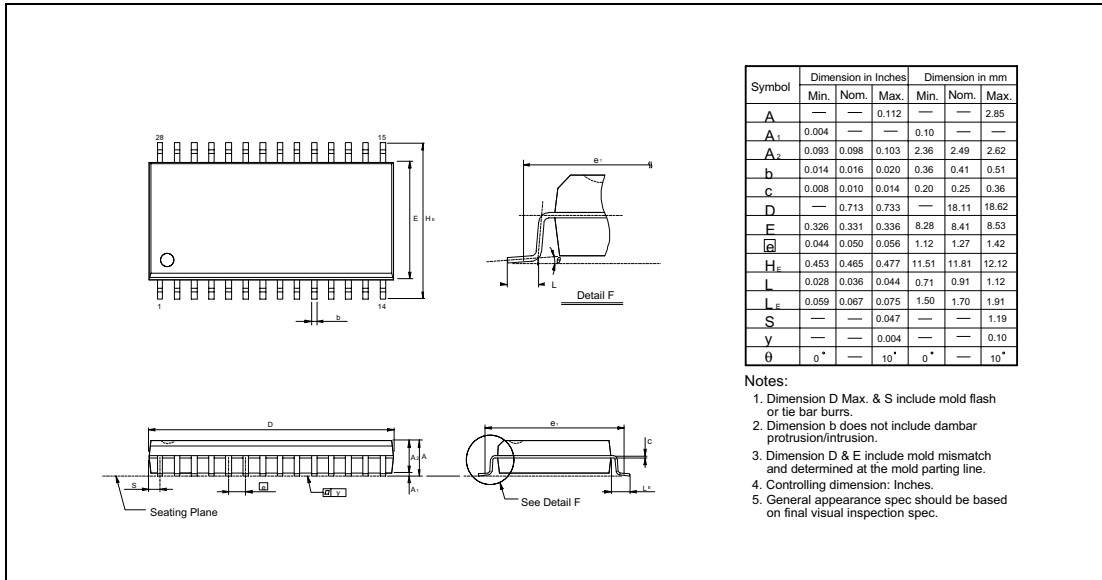
PAD NO.	X	Y
1	-232.25	1445.22
2	-351.70	1445.22
3	-471.15	1445.22
4	-590.60	1445.22
5	-710.05	1445.22
6	-829.50	1445.22
7	-992.79	1362.24
8	-992.79	-1306.11
9	-857.86	-1452.79
10	-738.41	-1452.79
11	-594.84	-1414.13
12	-451.06	-1414.13
13	-310.67	-1414.13
14	-171.78	-1405.28
15	24.45	-1405.28
16	151.80	-1414.13
17	298.07	-1414.13
18	443.28	-1414.13
19	588.20	-1414.13
20	732.84	-1414.13
21	871.11	-1452.79
22	992.75	-1312.15
23	992.75	1373.67
24	810.09	1445.22
25	690.64	1445.22
26	571.19	1445.22
27	451.74	1445.22
28	332.29	1445.22
29	120.25	1444.65
30	-93.23	1444.65

Note: For bare chip form (C.O.B.) applications, the substrate must be connected to VDD or left floating in the PCB layout.

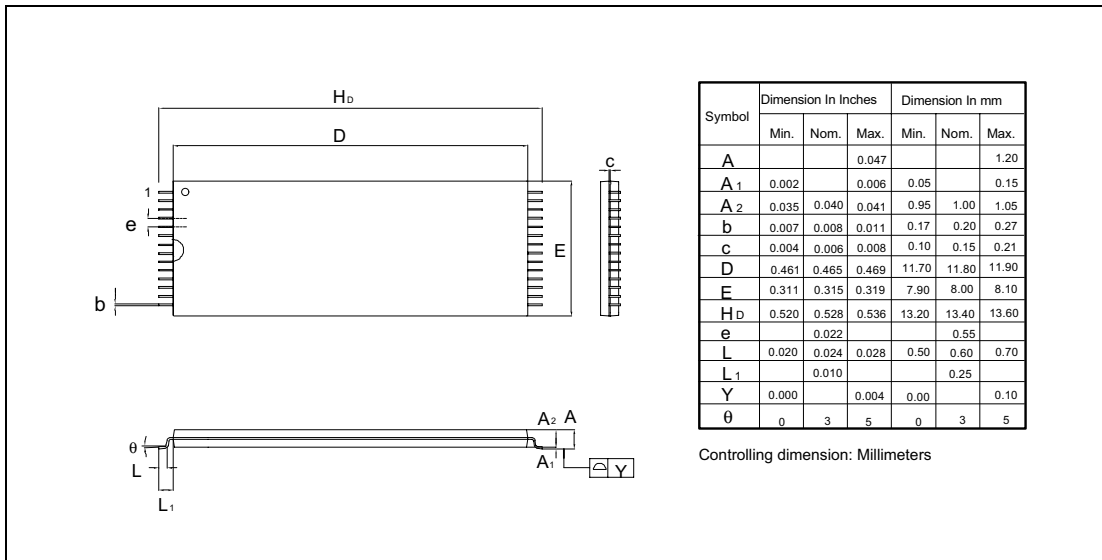


## PACKAGE DIMENSIONS

### 28-pin SO Wide Body



### 28-pin Standard Type One TSOP



**VERSION HISTORY**

VERSION	DATE	PAGE	DESCRIPTION
A12	Nov. 1999	1, 2, 7	Change the IDD, ISB, ISB1
		4, 7	Remove the W24257-10 spc.
A13	Apr. 2000	7	Typo correction in Standby Current Max.: mA->μA
A14	May 2000	1, 7, 8	Delete 28-pin DIP Package
		8	Add in Bonding Pad Diagram

**Headquarters**

No. 4, Creation Rd. III,  
Science-Based Industrial Park,  
Hsinchu, Taiwan  
TEL: 886-3-5770066  
FAX: 886-3-5796096  
<http://www.winbond.com.tw/>  
Voice & Fax-on-demand: 8862-27197006

**Taipei Office**

11F, No. 115, Sec. 3, MinSheng East Rd.,  
Taipei, Taiwan  
TEL: 886-2-27190505  
FAX: 886-2-27197502

**Winbond Electronics (H.K.) Ltd.**

Unit 9-15, 22F, Millennium City,  
No. 378 Kwun Tong Rd;  
Kowloon, Hong Kong  
TEL: 852-27513100  
FAX: 852-27552064

**Winbond Electronics North America Corp.**

**Winbond Memory Lab.**  
**Winbond Microelectronics Corp.**  
**Winbond Systems Lab.**  
2727 N. First Street, San Jose,  
CA 95134, U.S.A.  
TEL: 408-9436666  
FAX: 408-5441798

Note: All data and specifications are subject to change without notice.